



## **TE0803 Test Board**

**Revision:** v.18

**Date:** 06.05.2019 16:00

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Online version of this manual and other related documents can be found at <https://wiki.trenz-electronic.de/display/PD/Trenz+Electronic+Documentation>

## Overview

Design Example with minimum PS Setup (DDR, QSPI, UART0) only for custom boards or easier debug via SDK.

## Key Features

- QSPI
- SDK
- Custom Carrier (minimum PS Design with available module components only)
- Special FSBL for QSPI Programming

## Revision History

Date	Vivado	Project Built	Authors	Description
2018-05-17	2017.4	TE0803-test_board_noprebuilt-vivado_2017.4-build_09_20180517152118.zip TE0803-test_board-vivado_2017.4-build_09_20180517152103.zip	John Hartfiel	<ul style="list-style-type: none"> <li>• new assembly variant</li> </ul>
2018-04-11	2017.4	TE0803-test_board_noprebuilt-vivado_2017.4-build_07_20180411081821.zip TE0803-test_board-vivado_2017.4-build_07_20180411081757.zip	John Hartfiel	<ul style="list-style-type: none"> <li>• bugfix TE0803-01-04EG board part file</li> </ul>
2018-02-13	2017.4	TE0803-test_board_noprebuilt-vivado_2017.4-build_06_20180213120257.zip TE0803-test_board-vivado_2017.4-build_06_20180213120229.zip	John Hartfiel	<ul style="list-style-type: none"> <li>• new assembly variant</li> </ul>
2018-02-05	2017.4	TE0803-test_board-vivado_2017.4-build_05_20180205101915.zip TE0803-test_board_noprebuilt-vivado_2017.4-build_05_20180205101943.zip	John Hartfiel	<ul style="list-style-type: none"> <li>• new assembly variant</li> </ul>
2018-01-31	2017.4	TE0803-test_board-vivado_2017.4-build_05_20180131124202.zip TE0803-test_board_noprebuilt-vivado_2017.4-build_05_20180131124215.zip	John Hartfiel	<ul style="list-style-type: none"> <li>• new assembly variant</li> </ul>
2018-01-18	2017.4	TE0803-test_board-vivado_2017.4-build_05_20180118160549.zip TE0803-test_board_noprebuilt-vivado_2017.4-build_05_20180118160604.zip	John Hartfiel	<ul style="list-style-type: none"> <li>• rework Board Part Files</li> </ul>
2017-11-16	2017.2	TE0803-test_board-vivado_2017.2-build_05_20171116152716.zip TE0803-test_board_noprebuilt-vivado_2017.2-build_05_20171116154619.zip	John Hartfiel	<ul style="list-style-type: none"> <li>• Update Board Part CSV File with new Flash assembly variants</li> </ul>
2017-11-14	2017.2	TE0803-test_board-vivado_2017.2-build_05_20171114090712.zip TE0803-test_board_noprebuilt-vivado_2017.2-build_05_20171114090725.zip	John Hartfiel	<ul style="list-style-type: none"> <li>• Initial release</li> </ul>

## Release Notes and Know Issues

Issues	Description	Workaround	To be fixed version
No known issues	---	---	---

## Requirements

### Software

Software	Version	Note
Vivado	2017.4	needed
SDK	2017.4	needed

### Hardware

Basic description of TE Board Part Files is available on [TE Board Part Files](#).

Complete List is available on <design name>/board\_files/\*\_board\_files.csv

Design supports following modules:

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	Others	Notes
TE0803-ES1	es1	REV01	2GB	64MB		
TE0803-01-02EG-1E	2eg	REV01	2GB	64MB		
TE0803-01-02CG-1E	2cg	REV01	2GB	64MB		
TE0803-01-03EG-1E	3eg	REV01	2GB	64MB		
TE0803-01-03CG-1E	3cg	REV01	2GB	64MB		
TE0803-01-02EG-1EA	2eg	REV01	2GB	128MB		
TE0803-01-02CG-1EA	2cg	REV01	2GB	128MB		
TE0803-01-03EG-1EA	3eg	REV01	2GB	128MB		
TE0803-01-03EG-1EB	3egb	REV01	4GB	128MB		
TE0803-01-03CG-1EA	3cg	REV01	2GB	128MB		

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	Others	Notes
TE0803-01-04CG-1EA	4cg	REV01	2GB	128MB		
TE0803-01-04EV-1EA	4ev	REV01	2GB	128MB		
TE0803-01-04EV-1E3	4ev	REV01	2GB	128MB	1mm connector contribution to stacking height	
TE0803-01-04EG-1EA	4eg	REV01	2GB	128MB		
TE0803-01-04CG-1EB	4cg	REV01	2GB	256MB		
TE0803-01-05EV-1EA	5ev	REV01	2GB	128MB		
TE0803-01-05EV-1IA	5ev_i	REV01	2GB	128MB		

Note: Design contains also Board Part Files for TE0803+TEBF0808 configuration, this board part files are not used for this reference design. \* Only different Flash size.

Design supports following carriers:

Carrier Model	Notes
Custom PCB	use simple Board Part files, if MIO connected is different to TEBF0808
TEBF0808	Used as reference carrier.
TEBT0808	Change UART0 to UART1 (MIO68...69) and regenerate design

Additional HW Requirements:

Additional Hardware	Notes
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## Content

For general structure and of the reference design, see [Project Delivery](#)

## Design Sources

Type	Location	Notes
Vivado	<design name>/block_design <design name>/constraints <design name>/ip_lib	Vivado Project will be generated by TE Scripts
SDK/HSI	<design name>/sw_lib	Additional Software Template for SDK/HSI and apps_list.csv with settings for HSI

## Additional Sources

Type	Location	Notes
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## Prebuilt

File	File-Extension	Description
BIF-File	*.bif	File with description to generate Bin-File
BIN-File	*.bin	Flash Configuration File with Boot-Image (Zynq-FPGAs)
BIT-File	*.bit	FPGA (PL Part) Configuration File
Diverse Reports	---	Report files in different formats
Hardware-Platform-Specification-Files	*.hdf	Exported Vivado Hardware Specification for SDK/HSI and PetaLinux
LabTools Project-File	*.lpr	Vivado Labtools Project File
Software-Application-File	*.elf	Software Application for Zynq or MicroBlaze Processor Systems

## Download

Reference Design is only usable with the specified Vivado/SDK/PetaLinux/SDx version. Do never use different Versions of Xilinx Software for the same Project.

Reference Design is available on:

- [TE0803 "Test Board" Reference Design](#)

## Design Flow



Reference Design is available with and without prebuilt files. It's recommended to use TE prebuilt files for first lunch.

Trenz Electronic provides a tcl based built environment based on Xilinx Design Flow.

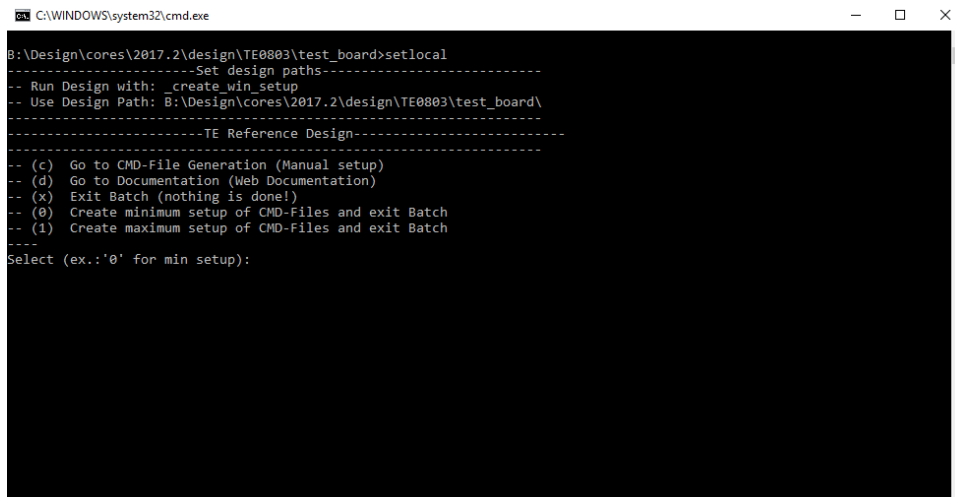
See also:

- [Vivado/SDK/SDSoC#XilinxSoftware-BasicUserGuides](#)
- [Vivado Projects](#)
- [Project Delivery.](#)

The Trenz Electronic FPGA Reference Designs are TCL-script based project. Command files for execution will be generated with "\_create\_win\_setup.cmd" on Windows OS and "\_create\_linux\_setup.sh" on Linux OS.

TE Scripts are only needed to generate the vivado project, all other additional steps are optional and can also executed by Xilinx Vivado/SDK GUI. For currently Scripts limitations on Win and Linux OS see: [Project Delivery Currently limitations of functionality](#)

1. \_create\_win\_setup.cmd/\_create\_linux\_setup.sh and follow instructions on shell:



```

C:\WINDOWS\system32\cmd.exe
B:\Design\cores\2017.2\design\TE0803\test_board>setlocal
-----Set design paths-----
-- Run Design with: _create_win_setup
-- Use Design Path: B:\Design\cores\2017.2\design\TE0803\test_board\
-----TE Reference Design-----
-- (c) Go to CMD-File Generation (Manual setup)
-- (d) Go to Documentation (Web Documentation)
-- (x) Exit Batch (nothing is done!)
-- (0) Create minimum setup of CMD-Files and exit Batch
-- (1) Create maximum setup of CMD-Files and exit Batch
--
Select (ex.:\'0\' for min setup):
  
```

2. Press 0 and enter for minimum setup
3. (optional Win OS) Generate Virtual Drive or use short directory for the reference design (for example x:\<design name>)
4. Create Project
  - a. Select correct device and Xilinx install path on "design\_basic\_settings.cmd" and create Vivado project with "vivado\_create\_project\_guiemode.cmd"

Note: Select correct one, see [TE Board Part Files](#)

**Important:** Use Board Part Files, which **did not** ends with \*\_tebf0808
5. Create HDF and export to prebuilt folder



- a. Run on Vivado TCL: `TE::hw_build_design -export_prebuilt`  
Note: Script generate design and export files into `\prebuilt\hardware\<short dir>`. Use GUI is the same, except file export to prebuilt folder
6. Generate Programming Files with HSI/SDK
  - a. Run on Vivado TCL: `TE::sw_run_hsi`  
Note: Scripts generate applications and bootable files, which are defined in `"sw_lib\apps_list.csv"`
  - b. (alternative) Start SDK with Vivado GUI or start with TE Scripts on Vivado TCL: `TE::sw_run_sdk`  
Note: See [SDK Projects](#)

# Launch

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## Programming

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Check Module and Carrier TRMs for proper HW configuration before you try any design.

Xilinx documentation for programming and debugging: [Vivado/SDK/SDSoC-Xilinx Software Programming and Debugging](#)

### QSPI

1. Connect JTAG and power on carrier with module
2. Open Vivado Project with "vivado\_open\_existing\_project\_guiemode.cmd" or if not created, create with "vivado\_create\_project\_guiemode.cmd"
3. Type on Vivado TCL Console: TE::pr\_program\_flash\_binfile -swapp hello\_te0808  
Note: To program with SDK/Vivado GUI, use special FSBL (zynqmp\_fsbl\_flash) on setup

Use SDK instead of Vivado is also possible, see: [SDK Projects#Xilinx%22HelloWorld%22onZynqMP](#)

### SD

This does not work, because SD controller is not selected on PS.

### JTAG

Load configuration and Application with SDK Debugger into device, see:

- [SDK Projects](#)
- [SDK Projects#DebugSoftwareApplication](#)

## Usage

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QSPI Boot:

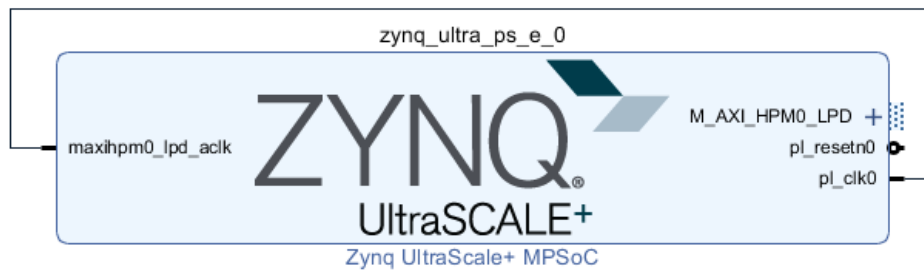
1. Prepare HW like described on section [46039162](#)
2. Connect UART USB (most cases same as JTAG)
3. Select QSPI Card as Boot Mode  
Note: See TRM of the Carrier, which is used.
4. Power On PCB  
Note: 1. ZynqMP Boot ROM loads PMU Firmware and FSBL from QSPI into OCM, 2. FSBL loads Application into DDR

Debugging:

- [SDK Projects](#)
- [SDK Projects#DebugSoftwareApplication](#)

# System Design - Vivado

## Block Design



## PS Interfaces

Activated interfaces:

Type	Note
DDR	
QSPI	MIO
UART0	MIO, please select other one, if you have connected uart to second controller or other MIO
SWDT0..1	
TTC0..3	

## Constraints

### Basic module constraints

```
_i_bitgen.xdc
```

```
set_property BITSTREAM.GENERAL.COMPRESS TRUE [current_design]
set_property BITSTREAM.CONFIG.UNUSEDPIN PULLNONE [current_design]
```

### Design specific constrain

Not needed.

# Software Design - SDK/HSI

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For SDK project creation, follow instructions from:

[SDK Projects](#)

## Application

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### **zynqmp\_fsbl**

Xilinx default FSBL

### **zynqmp\_fsbl\_flash**

TE modified 2017.4 FSBL

Changes:

- Set FSBL Boot Mode to JTAG
- Disable Memory initialisation

### **Hello TE0803**

Hello TE0803 is a Xilinx Hello World example as endless loop instead of one console output.

## Additional Software


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No additional software is needed.

## Appx. A: Change History and Legal Notices

### Document Change History

To get content of older revision got to "Change History" of this page and select older document revision number.

Date	Document Revision	Authors	Description
2018-10-26	v.18  Unbekanntes Makro: 'metadata'	John Hartfiel	<ul style="list-style-type: none"> <li>new assembly variant</li> </ul>
11.04.2018	v.13	John Hartfiel	<ul style="list-style-type: none"> <li>bugfix board part file</li> </ul>
03.04.2018	v.11	John Hartfiel	<ul style="list-style-type: none"> <li>new assembly variant</li> </ul>
2018-01-18	v.6	John Hartfiel	<ul style="list-style-type: none"> <li>Release 2017.4</li> </ul>
2017-11-16	v.4	John Hartfiel	<ul style="list-style-type: none"> <li>Update assembly versions with new Flash size</li> </ul>
2017-11-14	v.3	John Hartfiel	<ul style="list-style-type: none"> <li>Release 2017.2</li> </ul>
	All	John Hartfiel , Thorsten Trenz	

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